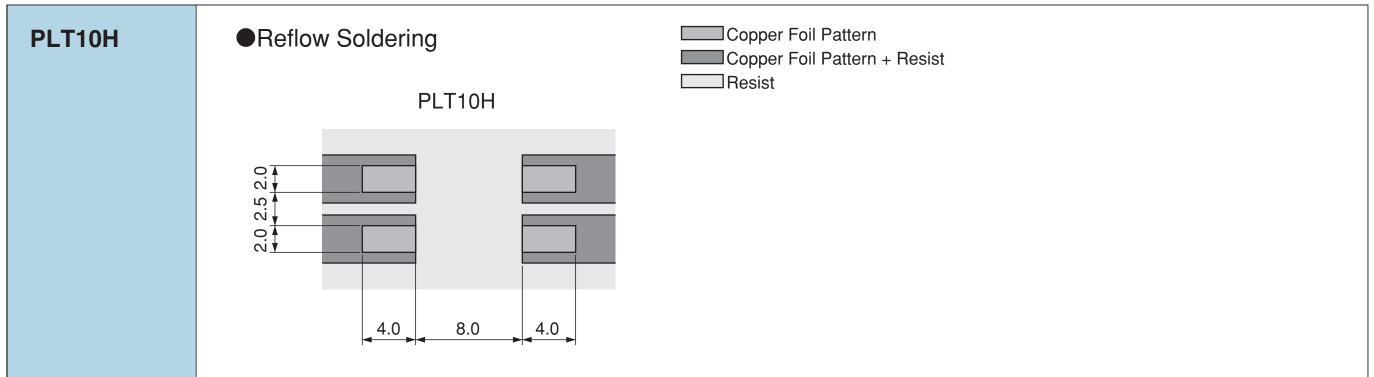
1. Standard Land Pattern Dimensions

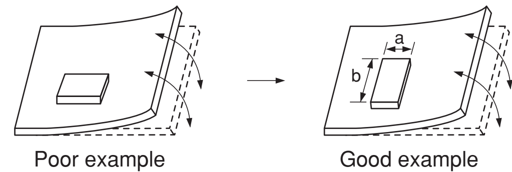
(in mm)



● PCB Warping

PCB should be designed so that products are not subjected to the mechanical stress caused by warping the board.

Products should be located in the sideways direction (Length: a<b) to the mechanical stress.



Poor example Good example

2. Solder Paste Printing and Adhesive Application

When reflow soldering the chip common mode choke coils, the printing must be conducted in accordance with the following cream solder printing conditions.
If too much solder is applied, the chip will be prone to damage by mechanical and thermal stress from the PCB and may crack.
Standard land dimensions should be used for resist and copper foil patterns.

When flow soldering the chip common mode choke coils, apply the adhesive in accordance with the following conditions.
If too much adhesive is applied, then it may overflow into the land or termination areas and yield poor solderability.
In contrast, if insufficient adhesive is applied, or if the adhesive is not sufficiently hardened, then the chip may become detached during flow soldering process.

Series	Solder Paste Printing
PLT10H	●Guideline of solder paste thickness: 150-200μm: PLT10H For the solder paste printing pattern, use standard land dimensions. *Solderability is subject to reflow conditions and thermal conductivity. Please make sure that your product has been evaluated in view of your specifications with our product being mounted to your product.

3. Standard Soldering Conditions

(1) Soldering Methods

Use reflow soldering methods only.
Use standard soldering conditions when soldering chip common mode choke coils.
In cases where several different parts are soldered, each having different soldering conditions, use those conditions requiring the least heat and minimum time.

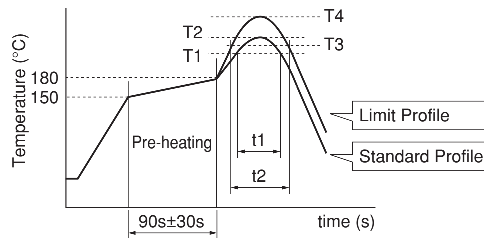
Solder: Use Sn-3.0Ag-0.5Cu solder. Use of Sn-Zn based solder will deteriorate performance of products.

Flux:
- Use Rosin-based flux.
- Do not use strong acidic flux (with chlorine content exceeding 0.20wt%)
- Do not use water-soluble flux.

For additional mounting methods, please contact Murata.

(2) Soldering Profile

●Reflow Soldering Profile
(Sn-3.0Ag-0.5Cu Solder)



Series	Standard Profile				Limit Profile			
	Heating		Peak Temperature (T2)	Cycle of Reflow	Heating		Peak Temperature (T4)	Cycle of Reflow
	Temp. (T1)	Time. (t1)			Temp. (T3)	Time. (t2)		
PLT10H	220°C min.	30 to 60s	250±3°C	2 times max.	230°C min.	60s max.	260°C/10s	2 times max.

(3) Reworking with Solder Iron

The following conditions must be strictly followed when using a soldering iron.
Pre-heating: 150°C 60s min.
Soldering iron power output / Tip diameter:
80W max. / ø3mm max.
Temperature of soldering iron tip / Soldering time / Times:
400°C max. / 5s / 2 times

Do not allow the tip of the soldering iron to directly contact the chip.
For additional methods of reworking with a soldering iron, please contact Murata engineering.

4. Cleaning

Do not clean after soldering. If cleaning, please contact us.